

ABSTRACT OF THE DISCLOSURE

A semiconductor package has a die pad, a die mounted on the die pad, a plurality of outer leads electrically connected to electrodes of the die by bonding wires, and a sealing member. The sealing member seals therein the die, the bonding wires, parts of the outer leads and a part of the die pad. Further the sealing member has an upper surface on the side of the die and a lower surface on the side of the die pad. The outer leads have upper connecting surfaces on the side of the upper surface of the sealing member, and lower connecting surfaces on the side of the lower surface of the sealing member. The outer leads have a height from a plane including the lower surface of the sealing member greater than that of the upper surface of the sealing member from the same plane.